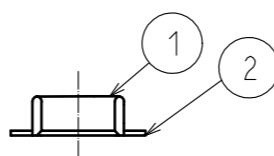
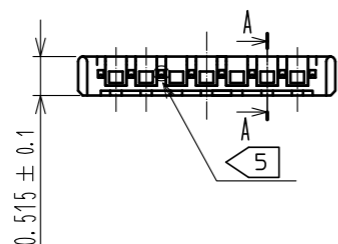
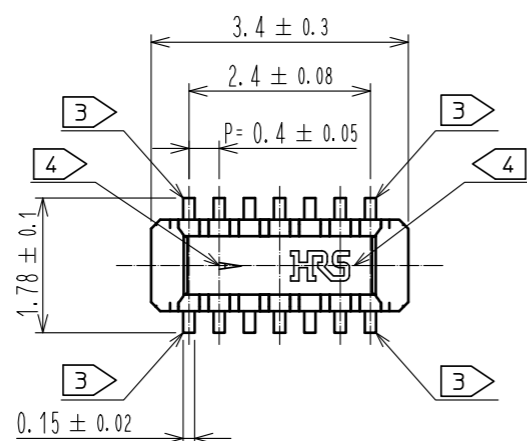
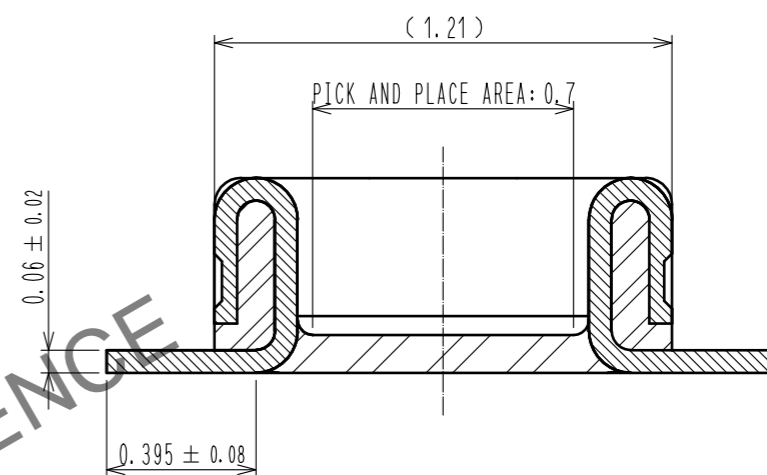


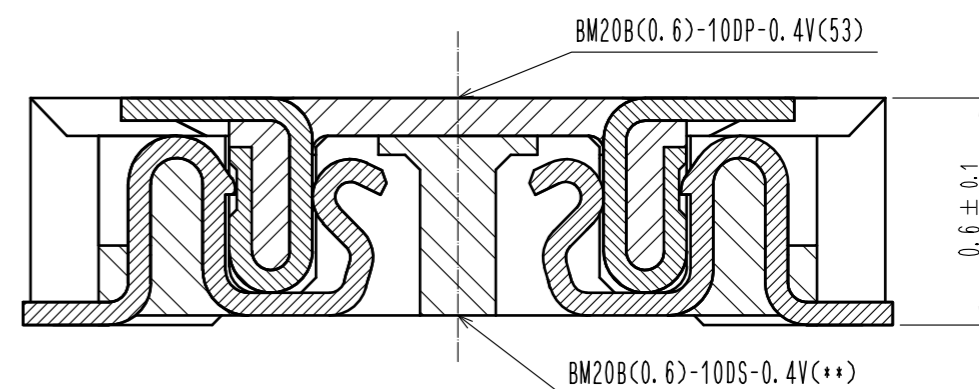
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A-A (50:1)



ENGAGEMENT FIGURE (50:1)

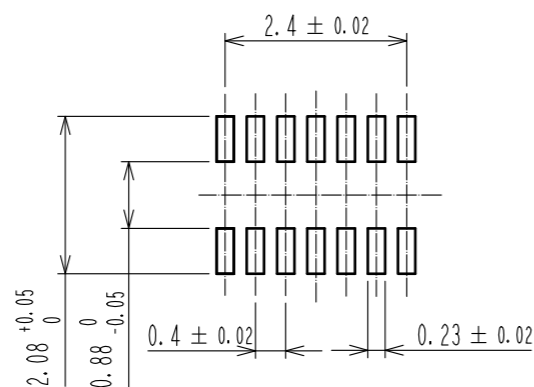


- NOTE 1 . ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX
- 2 CONTACT PLATING SPECIFICATIONS  
CONTACT AREA : GOLD 0.05 μm MIN  
SMT LEAD : GOLD 0.05 μm MIN  
UNDER PLATING : NICKEL 1 μm MIN  
( SURFACE : SEALING )
  - 3 EACH CONTACTS AT 4 CORNERS ARE PROVIDED FOR METAL FITTINGS.
  - 4 HRS MARK AND CAV No. ARE INDICATED IN APPROX POSITION SHOWN.
  - 5 A PART OF THE WALL COULD BE NOTCHED.

3	PS	CLEAR (EMBOSSED CARRIER TAPE)	6	PS	CLEAR (REINFORCEMENT COLLAR)
2	PHOSPHOR BRONZE	2	5	PS	BLACK (PLASTIC REEL)
1	LCP	UL94 V-0, BLACK	4	POLYESTER	CLEAR (COVER TAPE)
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
UNITS mm		SCALE 10 : 1		DESCRIPTION OF REVISIONS	
		APPROVED : MO. ISHIDA	16.02.22	DESIGNED	CHECKED
HIROSE ELECTRIC CO., LTD.		CHECKED : TS. MIYAZAKI	16.02.22	DATE	
		DESIGNED : NY. YAMASHIRO	16.02.22	DRAWING NO. EDC-347087-53-01	
		DRAWN : KR. AJITO	16.02.22	PART NO. BM20B(0.6)-10DP-0.4V(53)	
				CODE NO. CL684-9300-6-53	

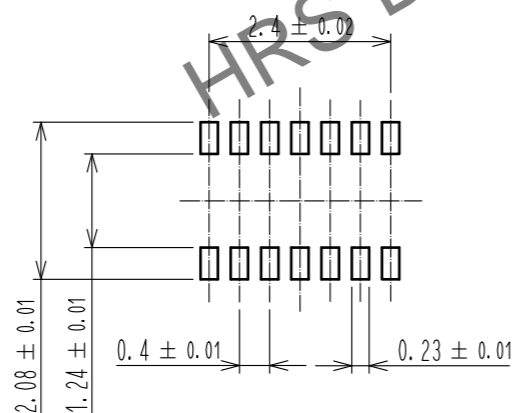
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◆ RECOMMENDED PCB LAYOUT

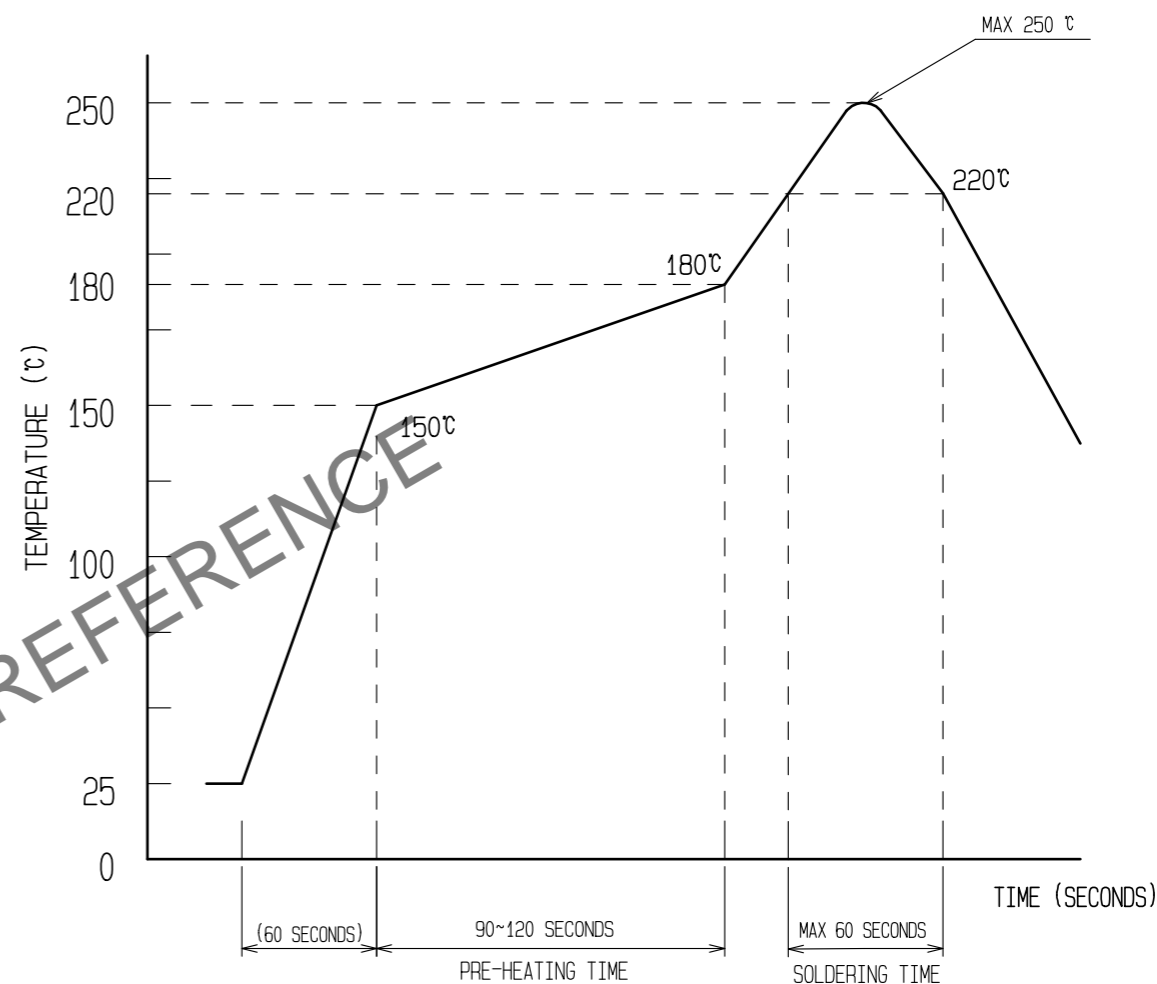


◆ RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS :  $100 \mu\text{m}$



6 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: IR REFLOW  
 NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.  
 1) REFLOW TIME  
 DURATION ABOVE 220°C: 60 SEC MAX.  
 (PEAK TEMPERATURE: 250°C MAX)  
 2) PRE-HEAT TIME  
 PRE-HEAT TEMPERATURE(MIN): 150°C  
 PRE-HEAT TEMPERATURE(MAX): 180°C  
 PRE-HEAT TIME: 90-120 SEC.

6 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

<b>HRS</b>	DRAWING NO.	EDC-347087-53-01
	PART NO.	BM20B(0.6)-10DP-0.4V(53)
	CODE NO.	CL684-9300-6-53

